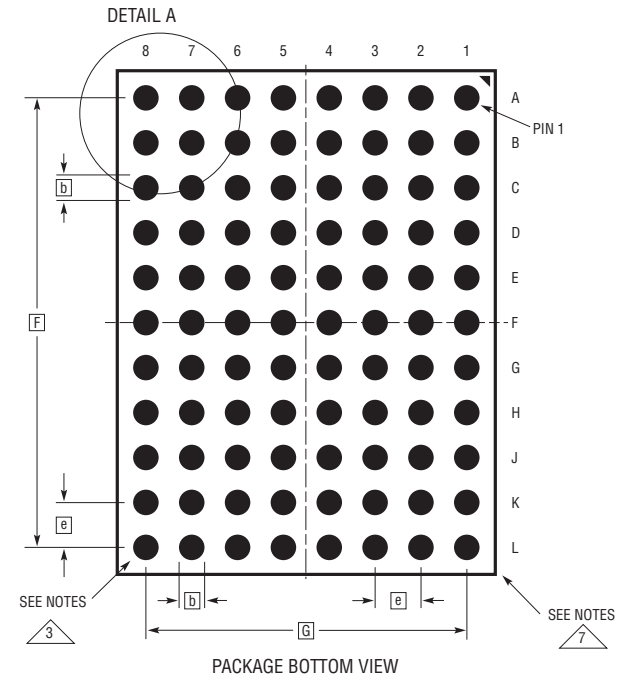
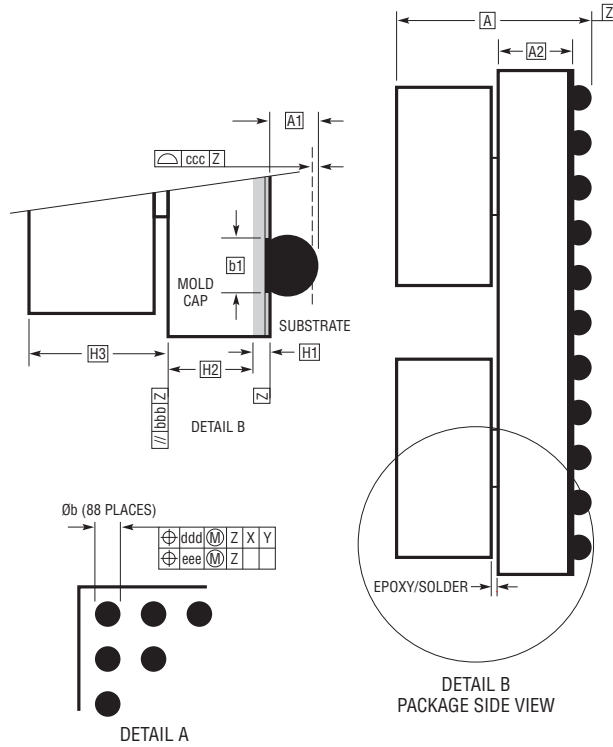
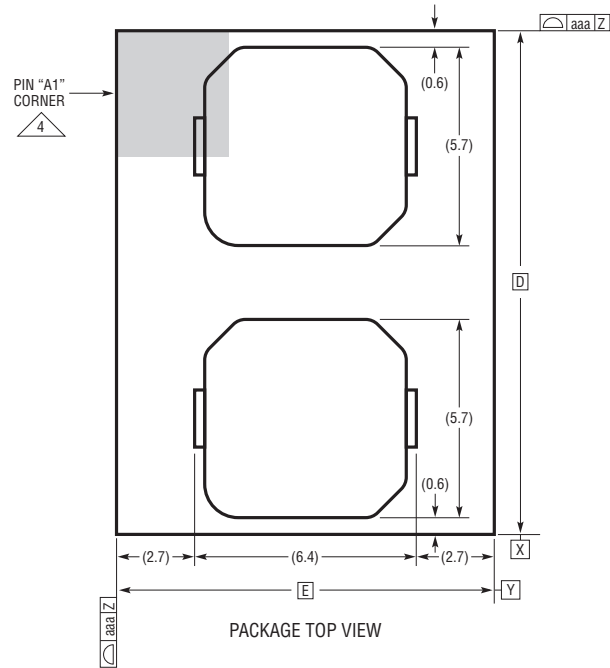


BGA Package
88-Lead (15mm × 11.25mm × 5.74mm)
 (Reference LTC DWG # 05-08-1526 Rev B)

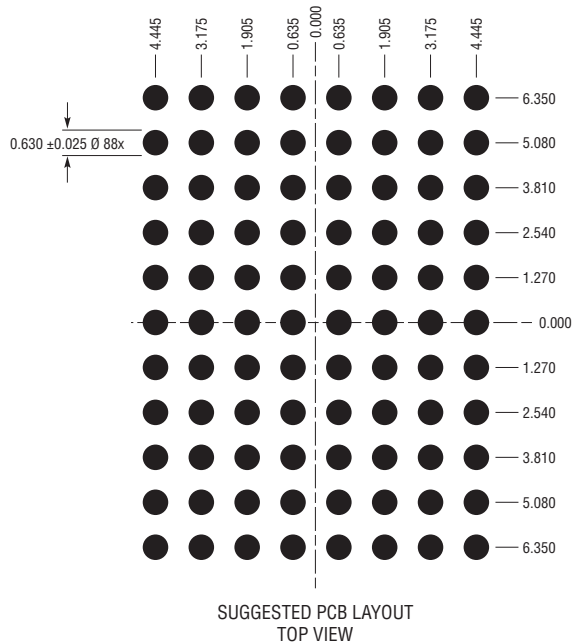


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE

- 3 BALL DESIGNATION PER JESD MS-028 AND JEP95
 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC

- 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	5.43	5.74	6.26	
A1	0.50	0.60	0.70	BALL HT
A2	2.23	2.32	2.41	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D		15.00		
E		11.25		
e		1.27		
F		12.70		
G		8.89		
H1	0.28	0.32	0.36	SUBSTRATE THK
H2	1.95	2.00	2.05	MOLD CAP HT
H3	2.70	2.82	3.15	INDUCTOR HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 88

